

**Preliminary Amendment**

Applicant: Jeffery S. Hess

Filed: Herewith

Docket No.: 10010488-2

Title: SUBSTRATE AND METHOD OF FORMING SUBSTRATE FOR FLUID EJECTION DEVICE

B2  
ok.

second portions of the opening to the other of the first portion and the plurality of second portions of the opening, and overetching each of the second portions of the opening at an interface between the first portion and each of the second portions of the opening, including communicating each of the second portions with an adjacent one of the second portions.

**IN THE ABSTRACT**

Please replace the Abstract with the following rewritten Abstract:

10010488-2 "020103"  
B3

--A method of forming an opening through a substrate includes etching a first portion of the opening into the substrate from a first side, etching a plurality of second portions of the opening into the substrate from a second side opposite the first side, continued etching of at least one of the first portion and the plurality of second portions of the opening to the other of the first portion and the plurality of second portions of the opening, and overetching each of the second portions of the opening at an interface between the first portion and each of the second portions of the opening, including communicating each of the second portions with an adjacent one of the second portions.

**IN THE CLAIMS**

Please cancel claims 1-71.

Please add new claims 72-112 as follows:

B4

72. (New) A method of forming an opening through a substrate, the method comprising: etching a first portion of the opening into the substrate from a first side; etching a plurality of second portions of the opening into the substrate from a second side opposite the first side; continued etching of at least one of the first portion and the plurality of second portions of the opening to the other of the first portion and the plurality of second portions of the opening; and